LOCTITE®

Module Assembly Adhesives

Product Name	Description	Key Attributes	Glass Transition Temperature, T_g (°C)	Coefficient of Thermal Expansion, CTE (ppm/°C)		Viscosity at 25°C (cP)	Modulus at 25°C (MPa)	Recommended Cure
				Below T_g	Above T_g			
UV + Thermal Cure								
LOCTITE 3217	Acrylated epoxy adhesive	• Designed for image sensor module assemblies and temperature sensitive electronics components • Fast cure at low temperatures	82	53	178	37,600	2,865	1 sec. at 100 mW/cm² + 30 min. at 60°C
LOCTITE ABLESTIK NCA 2200	Acrylated epoxy adhesive	• One component • Low viscosity • Fast cure at low temperatures • Good adhesion to a variety of substrates • Designed for image sensor module assemblies and temperature sensitive electronics components	97	43	150	9,000	5,000	2 sec. at 100 mW/cm² + 30 min. at 80°C
LOCTITE ABLESTIK NCA 2280	Acrylated epoxy adhesive	• One component • High thixotropic index • High viscosity • Black in color to prevent light penetration • Fast cure at low temperatures • Good adhesion to liquid crystal polymer (LCP) substrates • Designed for image sensor module assemblies and temperature sensitive electronics components	90	45	156	54,000	4,500	2 sec. at 100 mW/cm² + 30 min. at 80°C
LOCTITE ABLESTIK NCA 2280LV	Acrylated epoxy adhesive	• One component • High thixotropic index • Fast cure at low temperatures • Low transmittance • Good adhesion to liquid crystal polymer (LCP) substrates • Black in color to prevent light penetration • Designed for image sensor module assemblies and temperature sensitive electronics components	75	54	160	32,800	3,000	2 sec. at 100 mW/cm² + 30 min. at 80°C

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